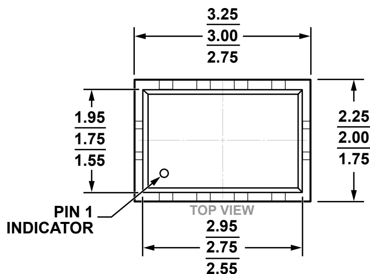
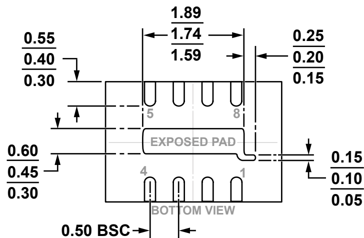
BILL OF MATERIALS (BOM)

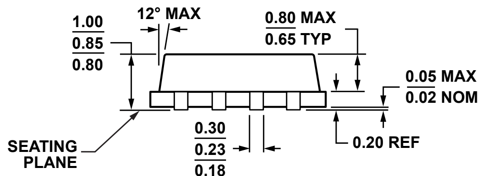
MATERIALS	FROM	TO	REMARKS
Die Attach Epoxy	Bell High Tech A3	Ablestik 8290	
Wire	Au	Au	Same
Mold Compound	Sumitomo G700	Sumitomo G700	Same
Leadframe	C194	C194	Same

ANALOG DEVICES

8-Lead Lead Frame Chip Scale Package [LFCSP_VD]
2 x 3 mm Body, Very Thin, Dual Lead
(CP-8-1)
Dimensions shown in millimeters



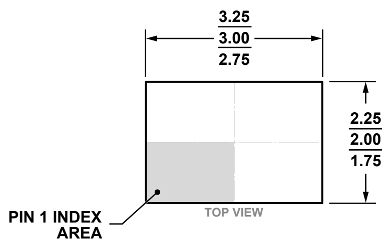


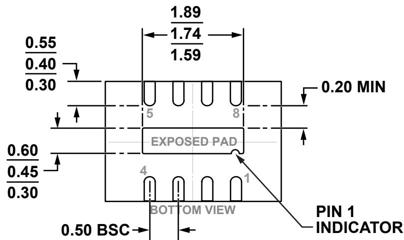


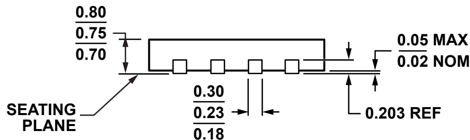
03-11-2013-B

ANALOG DEVICES

8-Lead Lead Frame Chip Scale Package [LFCSP_WD]
3 x 2 mm Body, Very Very Thin, Dual Lead
(CP-8-23)
Dimensions shown in millimeters







PKG-004467

02-12-2014-A

Conversion of 2x3mm LFCSP Package Outlines from Punch to Sawn and Transfer of Assembly Site to Amkor Philippines

2x3mm Sawn LFCSP at Amkor Philippines Qualification Results Summary

QUALIFICATION RESULT			
TEST	SPECIFICATION	SAMPLE SIZE	RESULT
Temperature Cycle (TC)*	JEDEC *JESD22-A104*	9 x 77	PASS
Highly Accelerated Stress Test (HAST)*	JEDEC *JESD22-A110*	9 x 77	PASS
Autoclave (AC)*	JEDEC *JESD22-A102*	9 x 77	PASS
Solder Heat Resistance (SHR)*	JEDEC/IPC *J-STD-020*	9 x 11	PASS
High Temperature Storage (HTS)	JEDEC *JESD22-A103*	3 x 77	PASS

*Preconditioned per JEDEC/IPC J-STD-020